



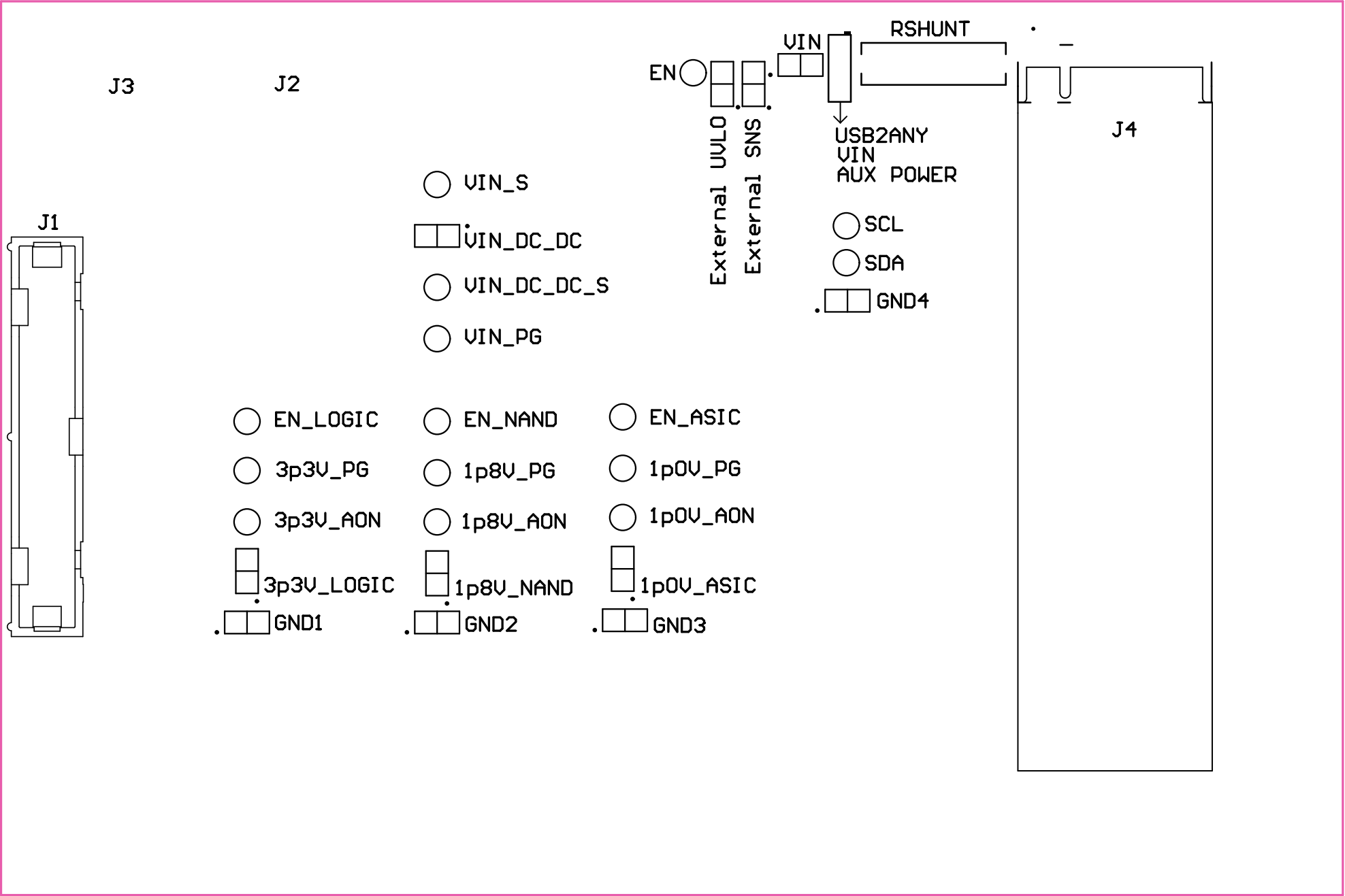
4000.00mil

6000.00mil

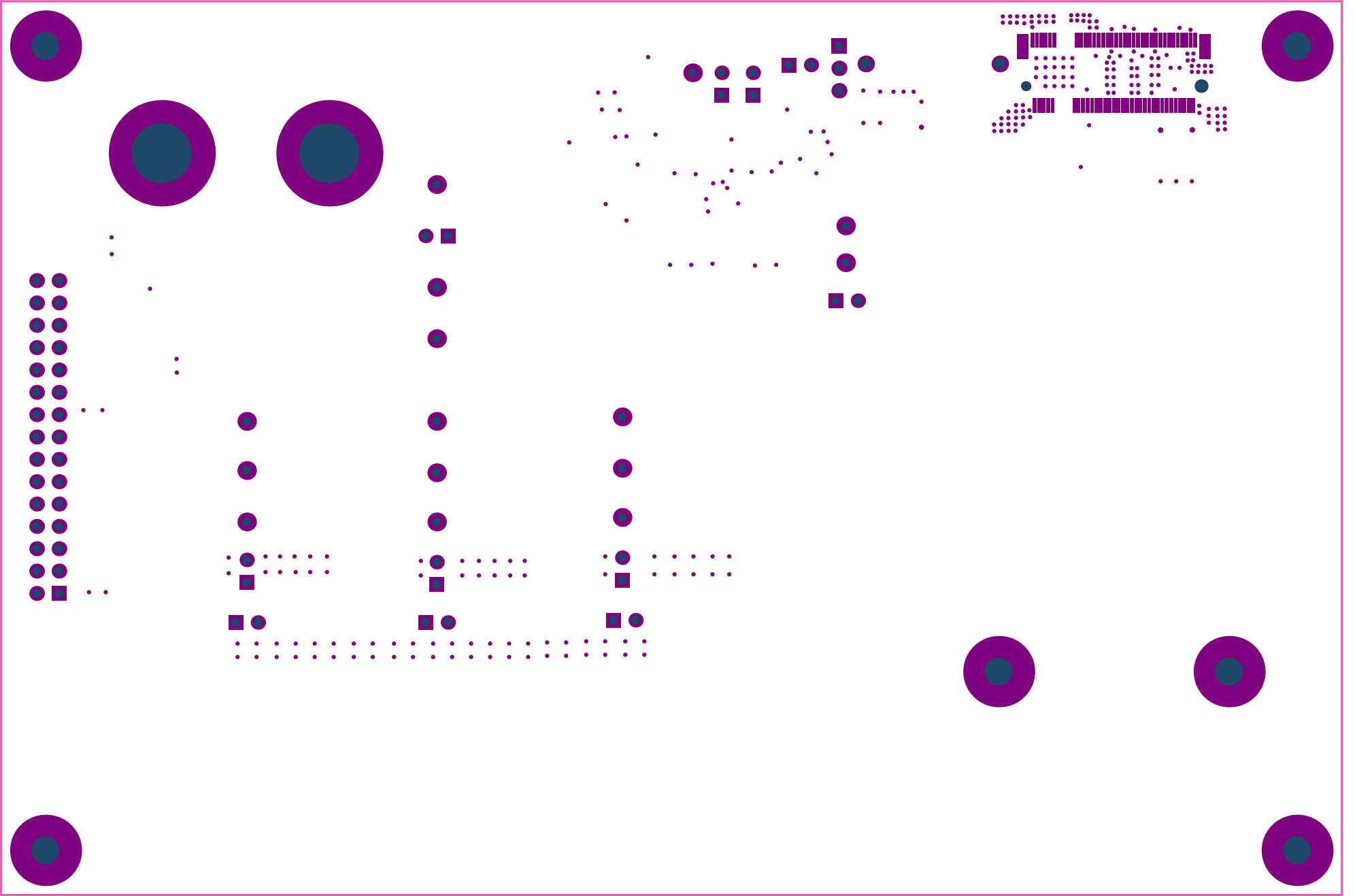


1000.00mil

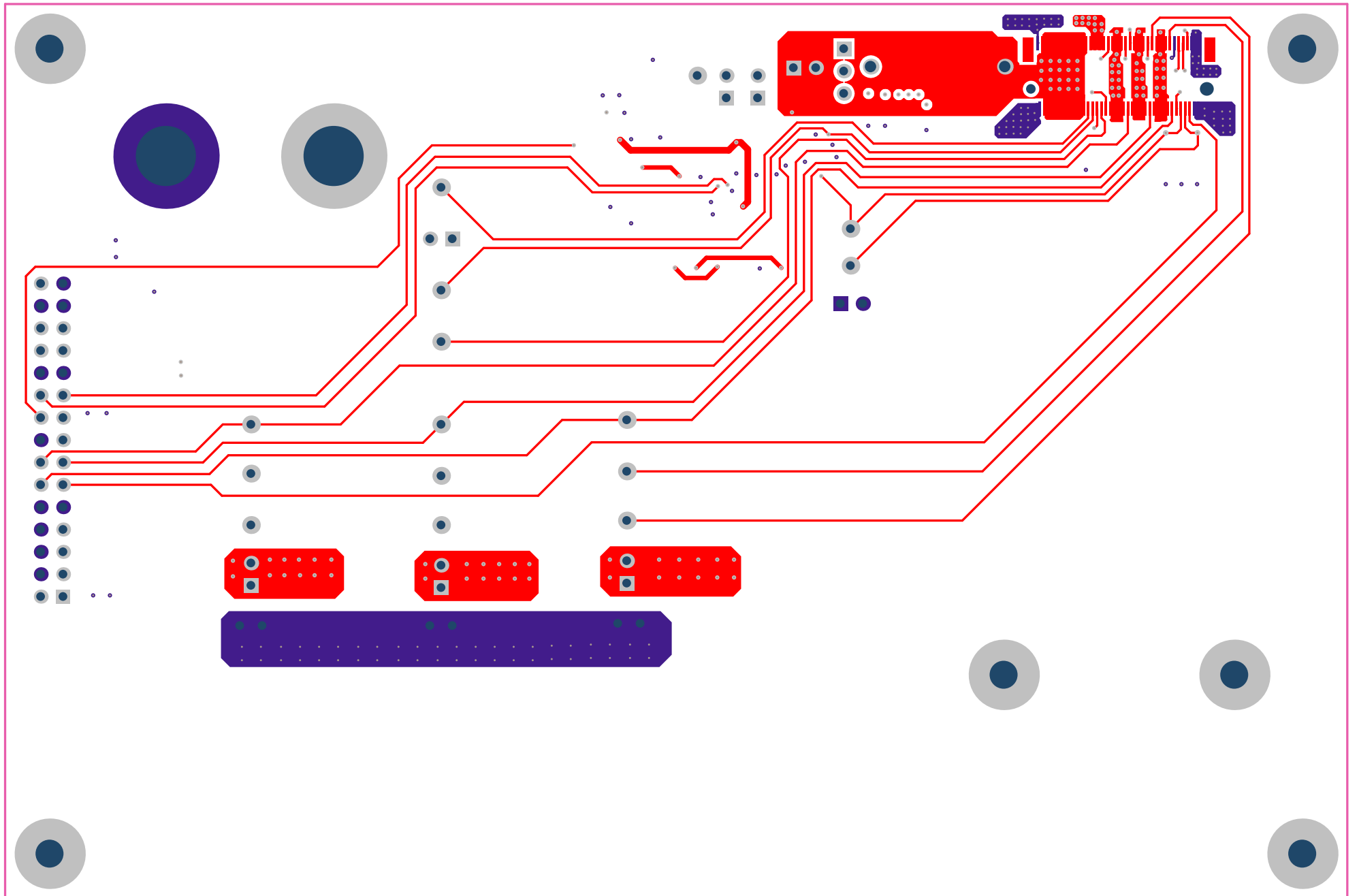
# Top Overlay



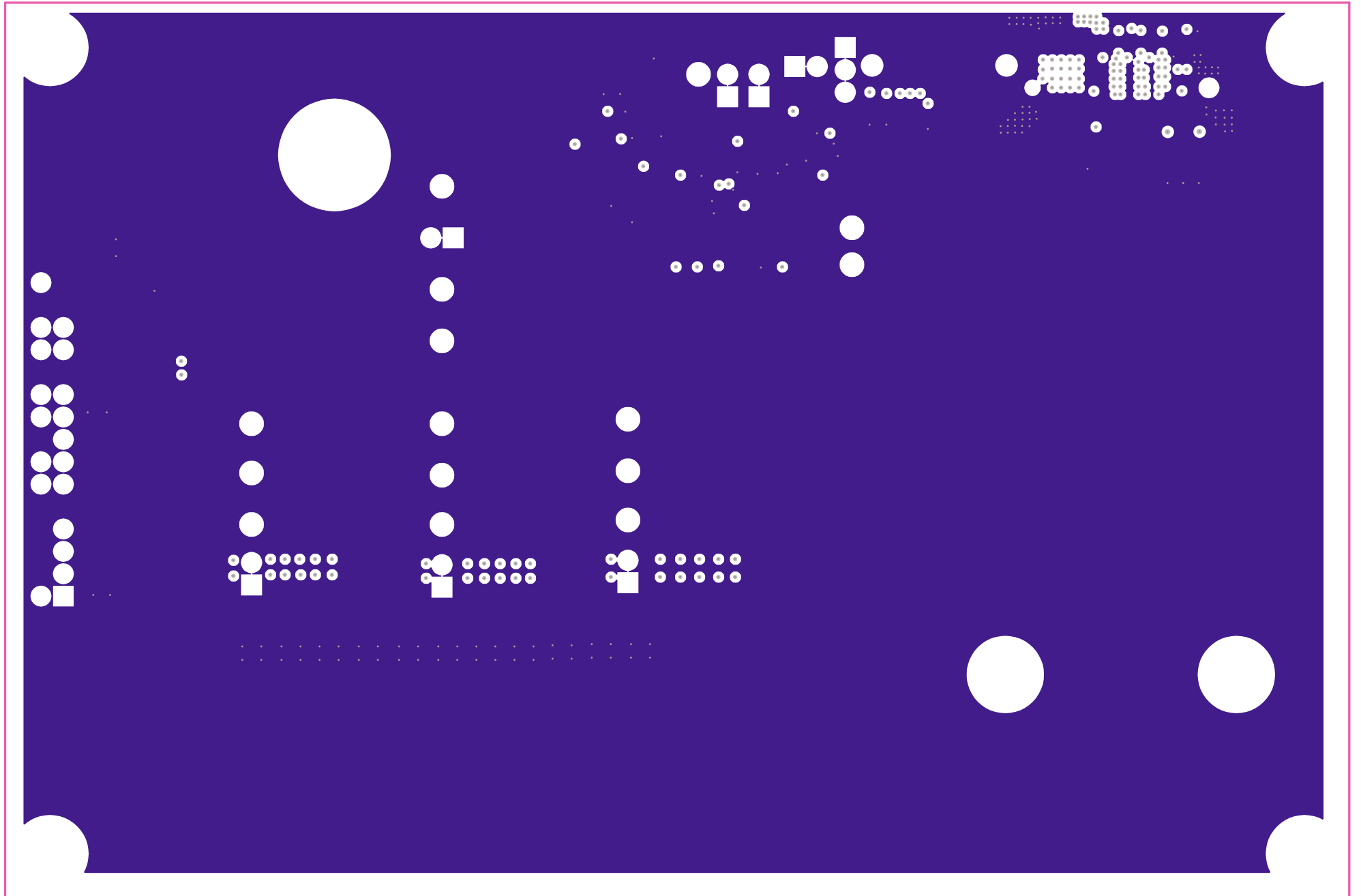
Top Solder



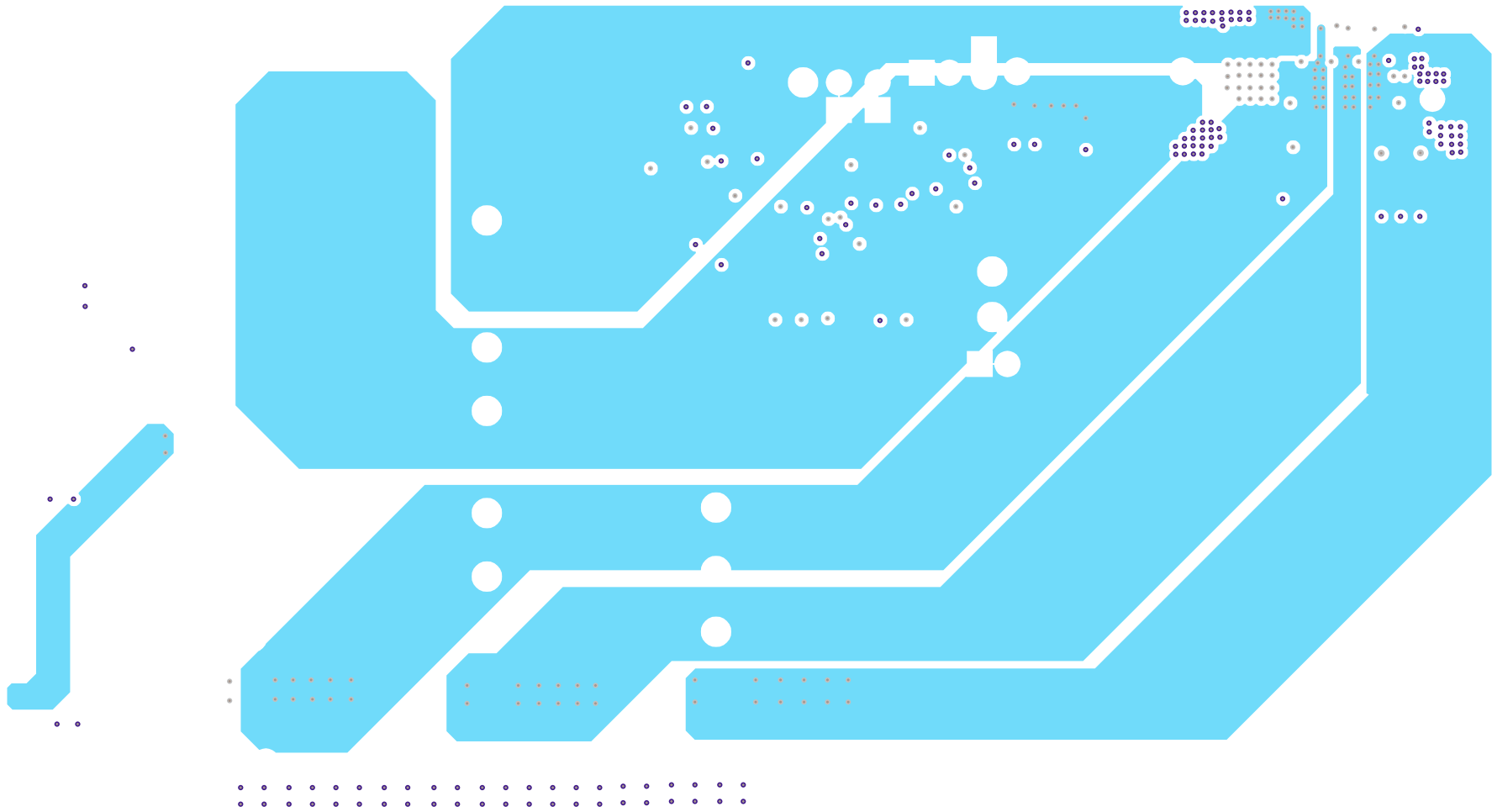
01\_Top Layer

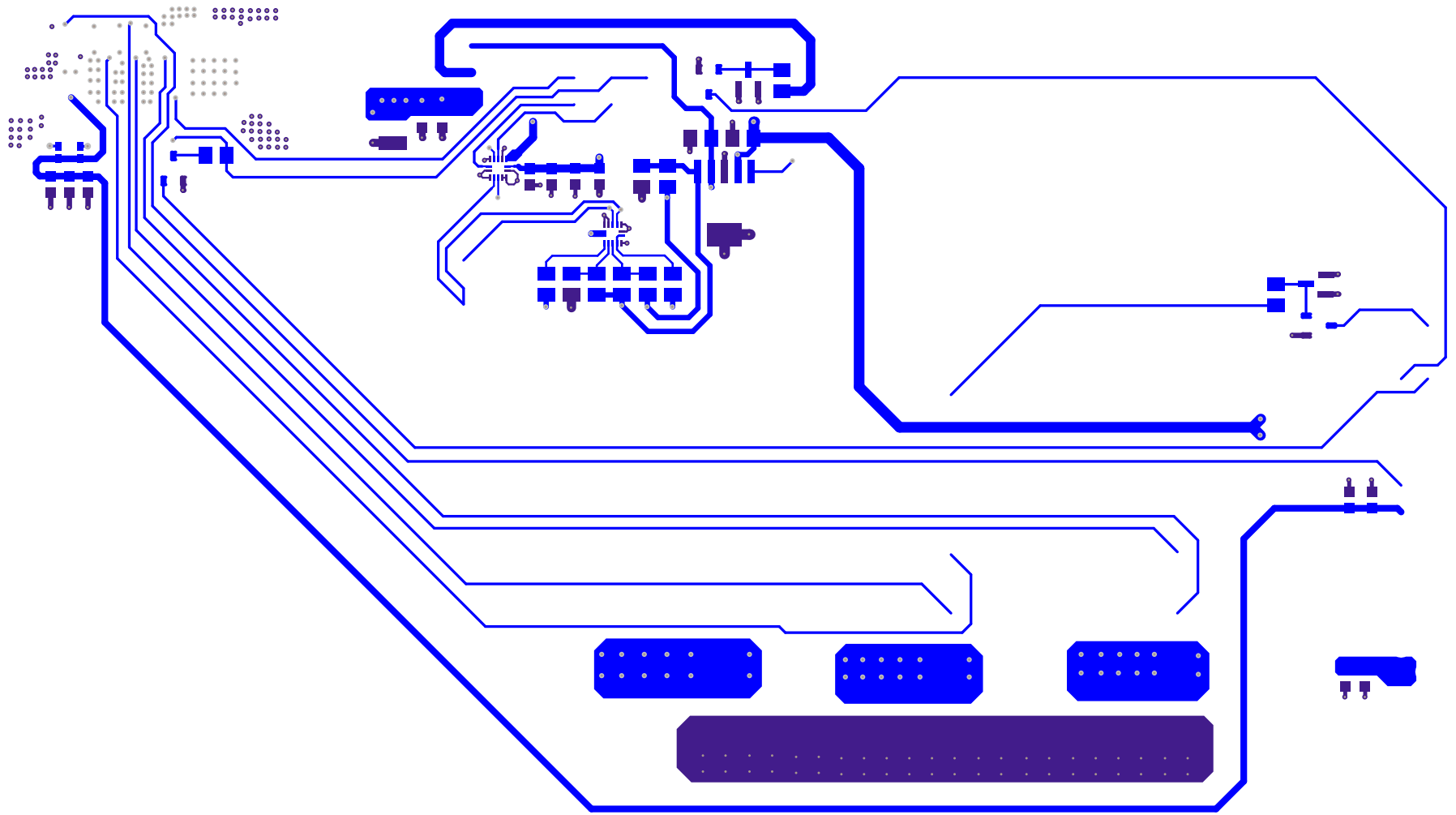


02\_GND



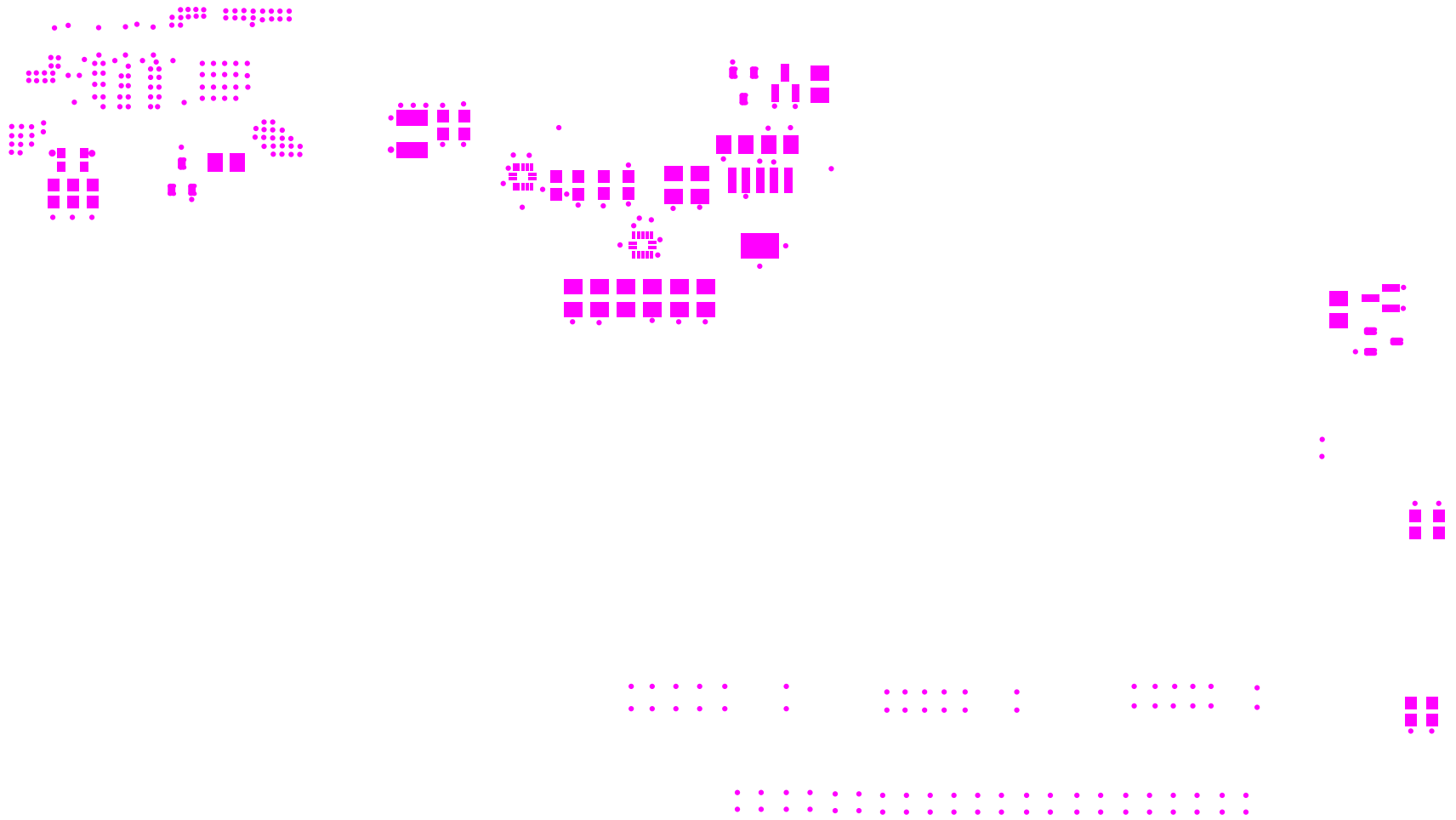
03\_PWR





UL94V-0  
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C3p3\_1 [ ] JRPJ2  
C3p3\_2 [ ] JRPJ1  
C3p3\_3 [ ]

Q1 [ ]  
REN\_PD [ ]

CIN1 [ ]  
CIN2 [ ]  
CIN3 [ ]

U1 [ ]

C2U1 [ ]  
C1U1 [ ]  
C1FB [ ]  
C2FB [ ]

RHA\_OUT [ ]  
RLA\_GND [ ]  
RLA\_ADJ [ ]  
RWA\_ADJ [ ]  
RWA\_OUT [ ]  
RHB\_ADJ [ ]

RFBL [ ]  
RFBH [ ]

Q2 [ ]  
C2\_LDO [ ]  
C1\_LDO [ ]  
D1 [ ]  
RD1 [ ]

U1\_LDO [ ]

RD2 [ ]  
Q3 [ ]  
D2 [ ]

C3J1 [ ]  
C4J1 [ ]

C1J1 [ ]  
C2J1 [ ]

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